

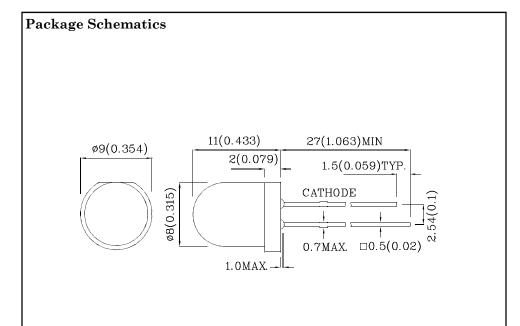
8mm ROUND LED LAMP

## **Features**

- Radial / Through hole package
- $\bullet$  Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant







#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{\mathrm{R}}$	5	V		
Forward Current	$I_{\mathrm{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\mathrm{FS}}$	160	mA		
Power Dissipation	$P_D$	75	mW		
Operating Temperature	T <sub>A</sub> -40 ~ +85		$^{\circ}\mathrm{C}$		
Storage Temperature	Tstg	-40 ~ +85	C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

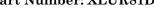
Operating Characteristics ( $T_A=25$ °C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λΡ	627	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20\text{mA})$	λD	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$\triangle \lambda$	45	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUR81D	Red	GaAsP/GaP	Red Diffused	50	98	627	30°

Mar 29,2011

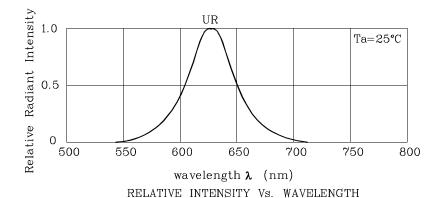
XDSA2420 V5 Layout: Maggie L.

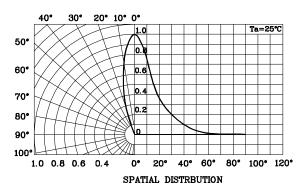
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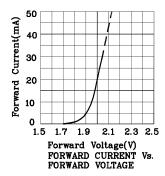


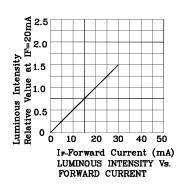


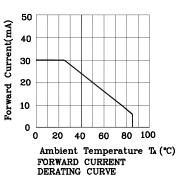


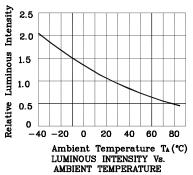


### **♦** UR

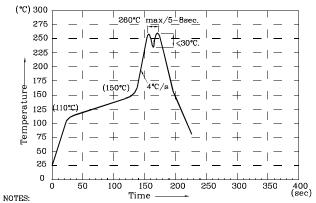








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- 1.Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C. 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once

# Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.





# PACKING & LABEL SPECIFICATIONS

